



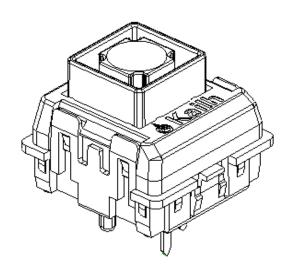


# **Document Number:**

KH-PS1703-40

# 产品规格书

# Product Specification



P/IN:		
	CDC150201C10	

Title:

#### CPG159301S10

## PG1593keyboardSwitch

Rev.	ECN	Release and Revision Description:	PreparedBy/Date:	Checked By/Date:	Approved By/Date:
A		New releasing 初版发行	吴川东 2018-05-05	胡远锋 2018-05-05	王锋 2018-05-05





# **Product Specification**

**P/N: DOC. No.:** CPG159301S10 KH-PS-1703-40

Rev.:

Page: 2/11

# Content

目	录	
1.	Scope/范围:	3
2.	Product Application/产品应用:	3
3.	Technology Parameters/技术参数	3
4.	Ratings/额定性能要求	3
5.	Profile Dimensions /外形尺寸	3
6.	Electrical Performance/电气性能	4
7.	Mechanical Performance/机械性能	5
8.	Environmental Performance/环境性能	7
	Recommended PCB Layout/推荐的 PCB 安装焊盘规格	
10.	Loading Parameter Specification/荷重参数规格	9
11.	Packaging/包装	.11
	Precaution/注音車面	



# KAIHUA EELETRONICS

### **Product Specification**

Page:

3/11

P/N: DOC. No.: Rev.: Α CPG159301S10 KH-PS-1703-40

### 1. Scope/范围:

This Product Specification covers the requirement of Mechanical keyboard switch on product performance, test methods and quality assurance provisions.

本规格书内容涵盖机械键盘开关产品的要求,包括性能指标、测试方法及质量保证方面等。

### Product Application/产品应用:

Mainly applied on computer keyboards, cash registers equipment and Man-Machine interface.

主要适用于电脑, 收银机, 工业设备和人机界面

### Technology Parameters/技术参数

Ambient Humidity 工作湿度:

Operating Temperature Range 使用温度范围:

Storage Temperature Range 保存温度范围:

Normal Condition:

Ambient temperature 环境温度:

Relative humidity 相对湿度:

Air pressure 气压:

Contact Resistance 接触阻抗:

Operation Force 操作力:

Solder Ability 可焊性:

Withstand Soldering Temperature 耐焊接热:

45~95% R.H.:

-10℃~+60℃:

-20℃~+70℃;

20+2°C

 $85\% \pm 5\%$  R.H.;

86~101KPa:

100 m  $\Omega$  Max;

 $55 \pm 10 \text{ af}$ :

 $245\pm5^{\circ}$ C, $3\pm0.5$ s;

260±5°C.5±1s:

#### Ratings/额定性能要求

Rating 额定负荷:

InsulationResistance 绝缘电阻:

Withstand Voltage 耐电压:

Mechanical Life 机械寿命:

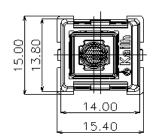
DC12V / 10mA;

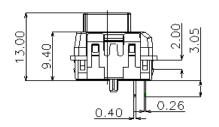
 $\geq$ 100M $\Omega$ /DC 500V;

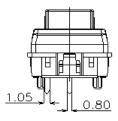
AC 100V 1 Minute;

50,000,000 Cycles.

### Profile Dimensions /外形尺寸









# **Product Specification**

**P/N: DOC. No.:** CPG159301S10 KH-PS-1703-40

Rev.:

**Page:** 4/11

### 6. Electrical Performance/电气性能

Itom	Description		
Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
6.1	Contact Resistance 接触电阻	Static load: (Operation force)x2, which is applied on the center of Switch stem. 静态负载: 动作力的 2 倍,施加在手柄中心.  Measurement tool: Contact resistance Meter. 测量工具: 微电流接触电阻计(1KHz, 20mV,5~50mA)  在低电流(≤100mA)条件下测试.  Measured at low current (100mA or less).	100mΩ Max 100mΩ以下
6.2	Insulation Resistance 绝缘电阻	Apply a Voltage of DC 500 V for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 500V DC 电压 1 分钟,按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.	100MΩ Min 100 兆欧以上
6.3	Dielectric withstanding voltage 耐电压	Apply a Voltage of AC 100 V (50~60Hz) for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 100V AC 电压 1 分钟,按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.	No evidence of breakdown 无瞬断、击穿等破坏.
6.4	Bouncing 触点抖动	Operation speed: 3~4 times/s 操作速度: 每秒 3~4 次 Slightly push the center of stem by 3~4 times/s, to test the bounce at "ON" and "OFF" 以每秒 3~4 次的速度,轻轻在手柄中心加力, 在"导通"与"瞬断"间测试. Oscillo scope 示波器 Switch Bouncing Test Circuit 抖动测定回路.	Before Life cycle: On:5ms MAX,5 毫秒以下 Off: 5ms MAX,5 毫秒以下 After Life cycle: On:10ms MAX,10 毫秒以下 Off: 10ms MAX,10 毫秒以下



Product Specification

DOC. No.: Rev.: Page

**P/N: DOC. No.:** ROCPG159301S10 KH-PS-1703-40

**Rev.:** A Page: 5/11

# 

### 7. Mechanical Performance/机械性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
7.1	Load curve 荷重曲线	Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止.  Force-Travel-diagram 操作力-行程-图解 120 100 80 pressure point 60 40 20 Travel 77 47 67 67 67 67 67 67 67 67 68 68 69 69 69 69 69 60 60 60 60 60 60 60 60 60 60 60 60 60	See page 10 见第 10 页
7.2	Loading Parameter 荷重参数	Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止.	See page 10 见第 10 页



# KAIHUA EELETRONICS

**Product Specification** 

DOC. No.: P/N: CPG159301S10

KH-PS-1703-40

Rev.:

Page:

Kaill	h		CPG159301S10	KH-PS	5-1703-40		
			ounting Surface	E II			
7.3	Static Strength 静止强度	A static load of 3 K direction of button of period of 60 second 在手柄动作方向施力后测试参数.	peration for a		No damag andmecha 电气和机械 Contact re 接触电阻:2 Contact for 30gf Min	nical) 《性能正常 sistance 200mΩ M	ax
7.4	Stem Pull Strength 手柄拉拔强 度	direction of stem op	e applied opposite to eration. 可垂直施加拉力,使其		500gf Min		
7.5	Shock 机械冲击	Measured by according condition: (1) Acceleration: 80 (2) Cycles of test:3 directions, for a total 试验次数: 每个方向	g 加速度 cycles each in 6	18 次.	Shall meet 满足 6,7		



# 凱華電子

**Product Specification** 

**P/N:**CPG159301S10

KH-PS-1703-40

Rev.:

**Page:** 7/11

		I I	
7.6	Life Test 寿命测试	(1) No load 无负载 (2) Operation speed: 5~6cycles/s 操作速度: 5~6 次/秒 (3) Push force: Maximum value of operation force. 按压力: 操作力规格值的上限. (4) Cycles: 50,000,000 times Min 操作次数: 5000 万次以上	Contact resistance: 200 m Ω Max 接触电阻: 200 毫欧以下 Bouncing: 10ms Max 触点抖动: 10 毫秒以下 Operation force: Variation rate within ±30% 操作力的变化范围在初始值的±30%以内.

### 8. Environmental Performance/环境性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
8.1	Cold test 耐寒性	<ul> <li>(1) Temperature: -20±2℃</li> <li>温度: -20±2℃</li> <li>(2) Duration of test: 48h</li> <li>持续时间: 48 小时</li> <li>(3) Take off a drop water 去掉水珠</li> <li>(4) Standard conditions after test: 1h</li> <li>试验后的放置条件: 1 小时</li> </ul>	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.2	Heat test 耐热性	<ul> <li>(1) Temperature: 70±2℃</li> <li>温度: 70±2℃</li> <li>(2) Duration of test: 48h</li> <li>持续时间: 48 小时</li> <li>(3) Take off a drop water 去掉水珠</li> <li>(4) Standard conditions after test: 1h</li> <li>试验后的放置条件: 1 小时</li> </ul>	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.3	Temperatur e cycle 温度循环	(1) Test cycles:5 cycles 试验周期: 5 个周期 (2) Standard condition after test:1h 试验后的放置条件: 1 小时  Temperature 温度 Duration of the 持续时间  20±5℃ 1h  20±5℃ 1h  20±5℃ 1h  60±5℃ 1h  70±5℃ 1h	Contact resistance: 200m Ω Max Shall meet :



**Product Specification** 

P/N: CPG159301S10

DOC. No.: Rev.: Page: 8/11 Α KH-PS-1703-40

8.4	Soldering heat test 耐焊接热	Soldering area: T/2 of PWB thickness. (PWB: T=1.6mm) 焊接面积: 印刷基板的 1/2 厚度处 Soldering temperature: 260±5℃ Soldering time: 3±0.5s 焊接温度: 260±5℃ 焊接时间: 3±0.5 秒	Appearance: No abnormality. 外观无异常
8.5	Solderability可焊性	1. Hand soldering 手工焊接: Please practice according to below condition: (1) Soldering Temperature: 350±5℃ 焊接温度: 350±5℃ (2) Continual soldering time: 3±0.5s 连续焊接时间: 3±0.5 秒 (3) Capacity of soldering iron: ≤20w 电烙铁功率: 20 瓦以下  2. Automatic PIPsoldering 自动波峰焊接: For the product of T/H, according to below condition:	At least 95% of surface area of immersed portion shall be covered by solder. 侵焊面积大于 95%以上.
8.6	Humidity test 耐湿性	<ul> <li>(1) Temperature: 60±2℃ 温度: 60±2℃</li> <li>(2) relative humidity: 90~95% R.H. 相对湿度:90~95% R.H.</li> <li>(3) Duration of test: 48h 持续时间: 48 小时</li> <li>(4) Take off a drop water 去掉水珠</li> <li>(5) Standard conditions after test: 1h 试验后的放置条件: 1 小</li> </ul>	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2



**Product Specification** 

DOC. No.: P/N: CPG159301S10

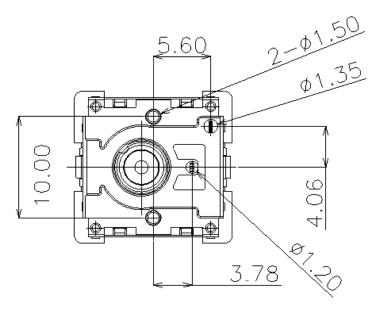
KH-PS-1703-40

Rev.: Page:

Apply the following environment to test: 根据下列条件进行测试:  (1) Temperature: 35±5℃ 温度: 35±5℃; 温度: 35±1%; (2) Salt water density: 5±1% 盐水浓度: 5±1%; (3) Duration: 12 hours 持续时间: 12 小时; (4) After test, the salt deposit shall be removed by running water. 实验后将盐沉积物用水冲掉  Apply the following environment to test: 根据下列条件进行测试  Appearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,无裸露基材.  Contact Resistance: 200 m Ω Max 接触电阻: 200 毫欧以下  Appearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,无裸露基材.  Withstand K₂S 硫化钾浓度: 2% (3) Duration: 2 minute. 持续时间: 2 分钟  Contact Resistance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,无裸露基材.  Contact Resistance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,无裸露基材.	ixaiii	•			
接续时间: 12 小时; (4) After test, the salt deposit shall be removed by running water. 实验后将盐沉积物用水冲掉  Apply the following environment to test: 根据下列条件进行测试 (1) Temperature: 35±5℃温度: 35±5℃ (2) K₂S Density: 2%; 硫化钾浓度: 2% (3) Duration: 2 minute. 持续时间: 2 分钟  Contact Resistance: 200 mΩ Max 接触电阻: 200 毫欧以下  Appearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点, 无裂纹, 无裸露基材.  Contact Resistance: 200 mΩ Max	8.7	• •	根据下列条件进行测试: (1) Temperature: 35±5℃ 温度: 35±5℃; (2) Salt water density: 5±1%	No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,	
根据下列条件进行测试  (1) Temperature: 35±5℃温度: 35±5℃  (2) K₂S Density: 2%;     硫化钾浓度: 2%  (3) Duration: 2 minute.     持续时间: 2 分钟  Rappearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点, 无裂纹, 无裸露基材.  Contact Resistance: 500 m Ω Max			持续时间: 12 小时; (4) After test, the salt deposit shall be removed by running water.	200 m Ω Max	
	8.8	K <sub>2</sub> S	根据下列条件进行测试 (1) Temperature: 35±5℃温度: 35±5℃ (2) K₂S Density: 2%;	No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点,无裂纹,无裸露基材.  Contact Resistance: 500 m Ω Max	

### Recommended PCB Layout 推荐的 PCB 安装焊盘规格

(Top View) (Single face board T=1.6mm)





# **Product Specification**

 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG159301S10
 KH-PS-1703-40
 A
 10/11

### 10. Loading Parameter (FP/OP/PT/OF/OT/MD/TF/RF/TT)Specification 荷重参数规格:

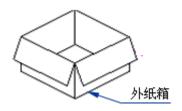
Parameter	Unit	Specification	Remark
FP(自由行程高)	mm	13±0.5	
OP (行程终止高度)	mm	11.4±1.0	
PT(导通行程)	mm	1.6±0.5	
OF (操作力)	gf	55±10	
OT(过行程)	mm	1.0	Min
MD (差动行程)	mm	0.5	Max
TF(接触力)	gf	65±10	
RF 回弹力	gf	13	Min
TT(总行程)	mm	3.6±0.5	

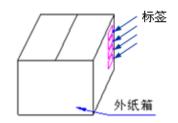
### 11. Packaging 包装

Packaging type:Tray, 1000Pcs/Tray, 4000Pcs/Carton.

包装方式:Tray 盘, 1000Pcs/盘, 4000Pcs/箱.







### 12.Precaution 注意事项

12.1 Soldering condition 浸焊条件

ITEM	CONDITION
· · =···	
项目	条件
Preheat temperature 预热温度	110℃ Max (Ambient temperature of soldering surface of P.W.B) 110℃以下(印刷基板焊锡面周围的温度)
Preheat time 预热时间	60s, Max 60 秒以内
Area of flux	1/2 Max of PWB Thickness
助焊剂面积	印刷基板厚度的 1/2 以内
Temperature of solder	260±5℃
焊锡温度	260±5℃
Time of immersion	Within 5s
浸焊时间	5 秒以内
Number of soldering	2time Max (But should down heat of the first soldering)
焊接次数	2 次以内
Printed wiring board	Single side copper-clad laminates
印刷基板	单面铜箔

(1) After switches were soldered, please be careful not to clean switches with solvent 开关浸焊后,注意不要用溶剂清洗.



### **Product Specification**

 P/N:
 DOC. No.:
 Rev.:
 Page:

 CPG159301S10
 KH-PS-1703-40
 A
 11/11

(2) Under the condition of using soldering iron, soldering temperature shall be 350℃ max within 3 sec. 在使用铬铁的情况下,焊锡温度应在350℃以下,焊接时间3秒以内.

#### 12.2 Notes 注意点

- (1) Please be cautious not to give excessive static load or shock to switches. 注意不要施加超负荷的压力或晃动开关.
- (2) Please be careful not to stack up P. W. B. after switches were soldered. 开关焊接以后,印刷基板注意不要叠放.
- (3) Preservation under high temperature and high humidity or corrosive gas should be avoided Especially. When you need to preserve for a long period, do not open the carton. 保管时尤其应注意避开高湿高温和有腐蚀性气体的环境.如需长时间保存,请不要打开包装箱.
- (4) Products meet the ROHS & REACH environmental management substances control standards 产品满足 ROHS & REACH 环境管理物质管制标准